

3A Dual High-Speed Power MOSFET Drivers

Features

- High Peak Output Current: 4.5A (typ)
- · Wide Input Supply Voltage Operating Range:
 - 4.5V to 18V
- · High Capacitive Load Drive Capability:
 - 1800 pF in 12 ns
- · Short Delay Times: 40 ns (typ)
- · Matched Rise/Fall Times
- · Low Supply Current:
 - With Logic '1' Input 1.0 mA (Max)
 - With Logic '0' Input 150 µA (Max)
- Low Output Impedance: 2.5Ω (typ)
- Latch-Up Protected: Will Withstand 1.5A Reverse Current
- Logic Input Will Withstand Negative Swing Up To 5V
- Pin compatible with the TC4423/TC4424/TC4425 and TC4426A/TC4427A/TC4428A devices
- Space-saving 8-Pin 150 mil body SOIC and 8-Pin 6x5 DFN Packages

Applications

- Switch Mode Power Supplies
- · Pulse Transformer Drive
- · Line Drivers
- · Direct Drive of Small DC Motors

General Description

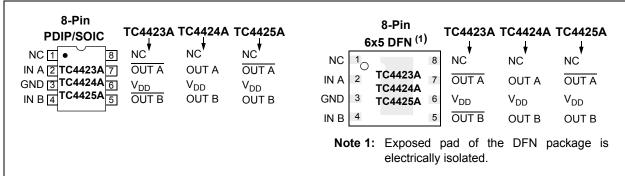
The TC4423A/TC4424A/TC4425A devices are a family of dual-output 3A buffers/MOSFET drivers. These devices are improved versions of the earlier TC4423/TC4424/TC4425 dual-output 3A driver family. This improved version features higher peak output current drive capability, lower shoot-throught current, matched rise/fall times and propagation delay times. The TC4423A/TC4424A/TC4425A devices are pincompatible with the existing TC4423/TC4424/TC4425 family. An 8-pin SOIC package option has been added to the family. The 8-pin DFN package option offers increased power dissipation capability for driving heavier capacitive or resistive loads.

The TC4423A/TC4424A/TC4425A MOSFET drivers can easily charge and discharge 1800 pF gate capacitance in under 20 ns, provide low enough impedances in both the on and off states to ensure the MOSFET's intended state will not be affected, even by large transients.

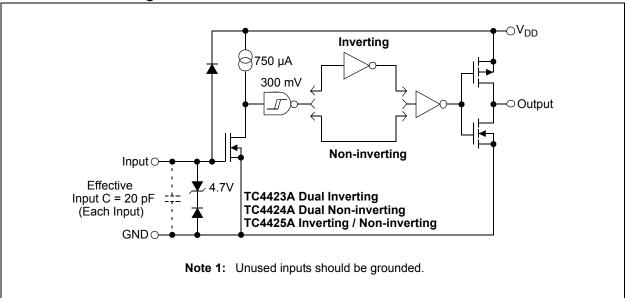
The TC4423A/TC4424A/TC4425A inputs may be driven directly from either TTL or CMOS (2.4V to 18V). In addition, the 300 mV of built-in hysteresis provides noise immunity and allows the device to be driven from slow rising or falling waveforms.

The TC4423A/TC4424A/TC4425A dual-output 3A MOSFET driver family is offerd with a -40°C to +125°C temperature rating, making it usful in any wide temperature range application.

Package Types



Functional Block Diagram⁽¹⁾



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage+20V Input Voltage, IN A or IN B(V_{DD} + 0.3V) to (GND – 5V)

† **Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS (NOTE 2)

Electrical Specifications: Unle	Electrical Specifications: Unless otherwise indicated, $T_A = +25^{\circ}C$, with $4.5V \le V_{DD} \le 18V$.								
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Input									
Logic '1', High Input Voltage	V _{IH}	2.4	1.5	_	V				
Logic '0', Low Input Voltage	V _{IL}	_	1.3	0.8	V				
Input Current	I _{IN}	-1	_	1	μΑ	$0V \le V_{IN} \le V_{DD}$			
Input Voltage	V _{IN}	-5	_	V _{DD} +0.3	V				
Output									
High Output Voltage	V _{OH}	$V_{DD} - 0.025$	_	_	V	DC Test			
Low Output Voltage	V _{OL}	_	_	0.025	V	DC Test			
Output Resistance, High	R _{OH}		2.2	3.0	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Output Resistance, Low	R _{OL}		2.8	3.5	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Peak Output Current	I _{PK}		4.5		Α	10V≤ V _{DD} ≤18V (Note 2)			
Latch-Up Protection With- stand Reverse Current	I _{REV}	_	>1.5	_	Α	Duty cycle \leq 2%, t \leq 300 µsec.			
Switching Time (Note 1)		•							
Rise Time	t _R	_	12	21	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF			
Fall Time	t _F	_	12	21	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF			
Delay Time	t _{D1}	_	40	48	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF			
Delay Time	t _{D2}	_	41	48	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF			
Power Supply									
Supply Voltage	V_{DD}	4.5	_	18	V				
Power Supply Current	I _S		1.0	2.0	mA	V _{IN} = 3V (Both inputs)			
Note 4 O Station Frances	Is	_	0.15	0.25	mA	V _{IN} = 0V (Both inputs)			

Note 1: Switching times ensured by design.

2: Tested during characterization, not production tested.

DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

Electrical Specifications: Unless otherwise indicated, operating temperature range with $4.5V \le V_{DD} \le 18V$.										
Parameters	Sym	Min	Тур	Max	Units	Conditions				
Input										
Logic '1', High Input Voltage	V_{IH}	2.4	_	_	V					
Logic '0', Low Input Voltage	V_{IL}		_	0.8	V					
Input Current	I _{IN}	-10	_	+10	μΑ	$0V \le V_{IN} \le V_{DD}$				
Output										
High Output Voltage	V _{OH}	V _{DD} – 0.025	_	_	V					
Low Output Voltage	V_{OL}	_	_	0.025	V					
Output Resistance, High	R _{OH}	_	3.1	6	Ω	I _{OUT} = 10 mA, V _{DD} = 18V				
Output Resistance, Low	R _{OL}	_	3.7	7	Ω	I _{OUT} = 10 mA, V _{DD} = 18V				
Switching Time (Note 1)										
Rise Time	t _R	_	20	31	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF				
Fall Time	t _F	_	22	31	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF				
Delay Time	t _{D1}	_	50	66	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF				
Delay Time	t _{D2}	_	50	66	ns	Figure 4-1, Figure 4-2, C _L = 1800 pF				
Power Supply										
Power Supply Current	I _S	_	2.0 0.2	3.0 0.3	mA	V _{IN} = 3V (Both inputs) V _{IN} = 0V (Both inputs)				

Note 1: Switching times ensured by design.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with 4.5V \leq V _{DD} \leq 18V.								
Parameters	Sym	Min	Тур	Max	Units	Conditions		
Temperature Ranges								
Specified Temperature Range (V)	T _A	-4 0	_	+125	°C			
Maximum Junction Temperature	T_J	_	_	+150	°C			
Storage Temperature Range	T _A	-65	_	+150	°C			
Package Thermal Resistances								
Thermal Resistance, 8L-6x5 DFN	$\theta_{\sf JA}$	_	33.2	_	°C/W	Typical four-layer board with vias to ground plane		
Thermal Resistance, 8L-PDIP	θ_{JA}	_	125	_	°C/W			
Thermal Resistance, 8L-SOIC	θ_{JA}	_	155	_	°C/W			

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

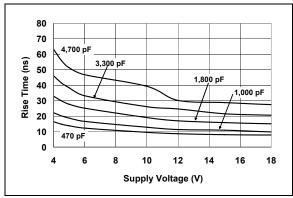


FIGURE 2-1: Rise Time vs. Supply Voltage.

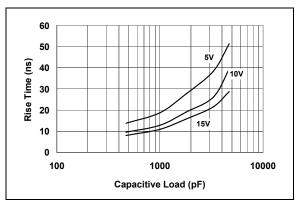


FIGURE 2-2: Rise Time vs. Capacitive Load.

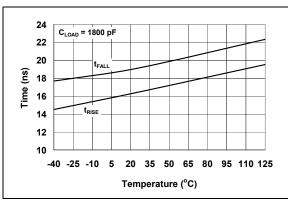


FIGURE 2-3: Rise and Fall Times vs. Temperature.

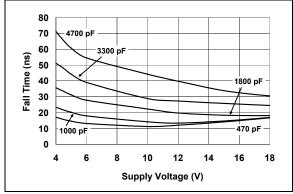


FIGURE 2-4: Fall Time vs. Supply Voltage.

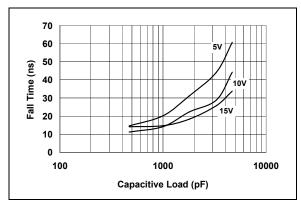


FIGURE 2-5: Fall Time vs. Capacitive Load.

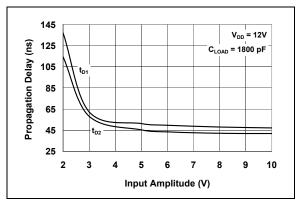


FIGURE 2-6: Propagation Delay vs. Input Amplitude.

Typical Performance Curves (Continued)

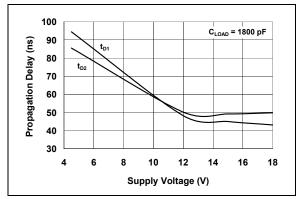


FIGURE 2-7: Propagation Delay Time vs. Supply Voltage.

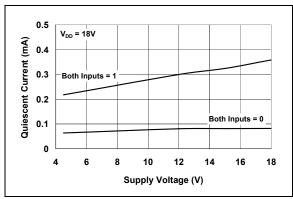


FIGURE 2-8: Quiescent Current vs. Supply Voltage.

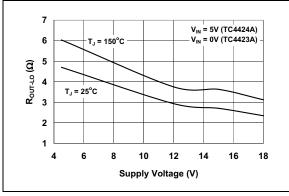


FIGURE 2-9: Output Resistance (Output Low) vs. Supply Voltage.

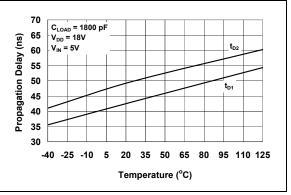


FIGURE 2-10: Propagation Delay Time vs. Temperature.

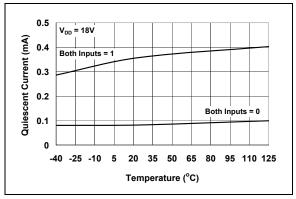


FIGURE 2-11: Quiescent Current vs. Temperature.

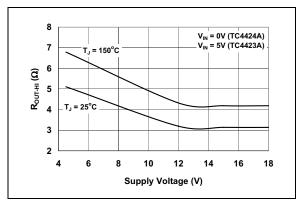


FIGURE 2-12: Output Resistance (Output High) vs. Supply Voltage.

Typical Performance Curves (Continued)

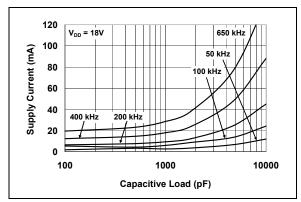


FIGURE 2-13: Supply Current vs. Capacitive Load.

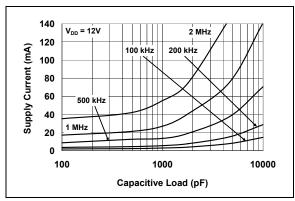


FIGURE 2-14: Supply Current vs. Capacitive Load.

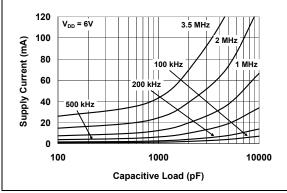


FIGURE 2-15: Supply Current vs. Capacitive Load.

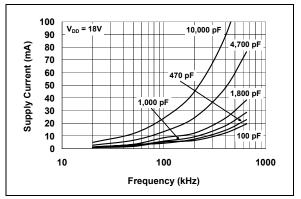


FIGURE 2-16: Supply Current vs. Frequency.

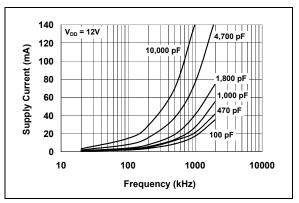


FIGURE 2-17: Supply Current vs. Frequency.

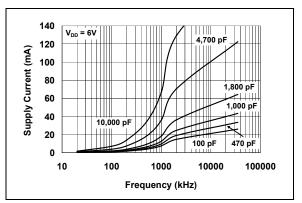


FIGURE 2-18: Supply Current vs. Frequency.

Typical Performance Curves (Continued)

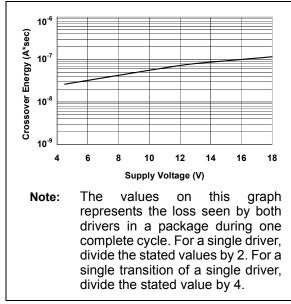


FIGURE 2-19: Crossover Energy vs. Supply Voltage.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE (1)

8-Pin PDIP, SOIC	8-Pin DFN	Symbol	Description
1	1	NC	No Connection
2	2	IN A	Input A
3	3	GND	Ground
4	4	IN B	Input B
5	5	OUT B	Output B
6	6	V_{DD}	Supply Input
7	7	OUT A	Output A
8	8	NC	No Connection
_	PAD	NC	Exposed Metal Pad

Note 1: Duplicate pins must be connected for proper operation.

3.1 Inputs A and B

Inputs A and B are TTL/CMOS compatible inputs that control outputs A and B, respectively. These inputs have 300 mV of hysteresis between the high and low input levels, allowing them to be driven from slow rising and falling signals, and to provide noise immunity.

3.2 Outputs A and B

Outputs A and B are CMOS push-pull outputs that are capable of sourcing and sinking 3A peaks of current (V_{DD} = 18V). The low output impedance ensures the gate of the external MOSFET will stay in the intended state even during large transients. These outputs also have a reverse current latch-up rating of 1.5A.

3.3 Supply Input (V_{DD})

 V_{DD} is the bias supply input for the MOSFET driver and has a voltage range of 4.5V to 18V. This input must be decoupled to ground with a local ceramic capacitor. This bypass capacitor provides a localized low-impedance path for the peak currents that are to be provided to the load.

3.4 Ground (GND)

Ground is the device return pin. The ground pin should have a low-impedance connection to the bias supply source return. High peak currents will flow out the ground pin when the capacitive load is being discharged.

3.5 Exposed Metal Pad

The exposed metal pad of the DFN package is not internally connected to any potential. Therefore, this pad can be connected to a ground plane or other copper plane on a printed circuit board to aid in heat removal from the package.

4.0 APPLICATIONS INFORMATION

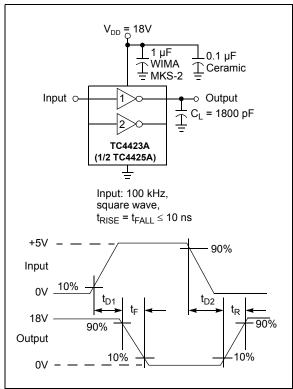


FIGURE 4-1: Inverting Driver Switching Time.

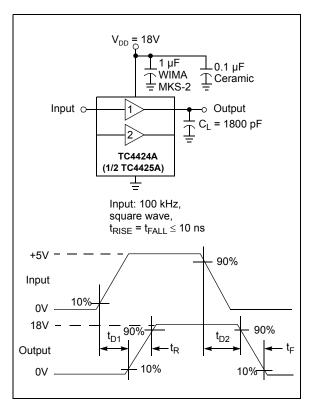


FIGURE 4-2: Non-inverting Driver Switching Time.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information (Not to Scale)

8-Lead DFN



Example:



8-Lead PDIP (300 mil)



Example:



8-Lead SOIC (150 mil)



Example:



Legend: XX...X Customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

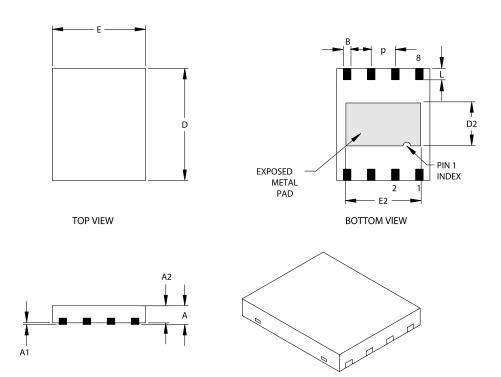
NNN Alphanumeric traceability code

e3 Pb-free JEDEC designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Dual-Flat, No-Lead Package (MF) 6x5 mm Body (DFN-S) - Saw Singulated



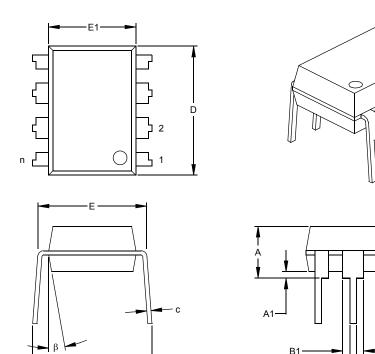
	Units		INCHES		М	ILLIMETERS*			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		8			8			
Pitch	р		.050 BSC			1.27 BSC			
Overall Height	Α	.033	.035	.037	0.85	0.90	0.95		
Package Thickness	A2	.031	.035	.037	0.80	0.89	0.95		
Standoff	A1	.000	.0004	.002	0.00	0.01	0.05		
Base Thickness	A3	.007	.008	.009	0.17	0.20	0.23		
Overall Length	E	.195	.197	.199	4.95	5.00	5.05		
Exposed Pad Length	E2	.152	.157	.163	3.85	4.00	4.15		
Overall Width	D	.234	.236	.238	5.95	6.00	6.05		
Exposed Pad Width	D2	.089	.091	.093	2.25	2.30	2.35		
Lead Width	В	.014	.016	.019	0.35	0.40	0.47		
Lead Length	L	.024		.026	0.60		0.65		

Notes:

JEDEC Equivalent: M0-220 Drawing No. C04-122

Revised 11/3/03

8-Lead Plastic Dual In-line (PA) - 300 mil Body (PDIP)



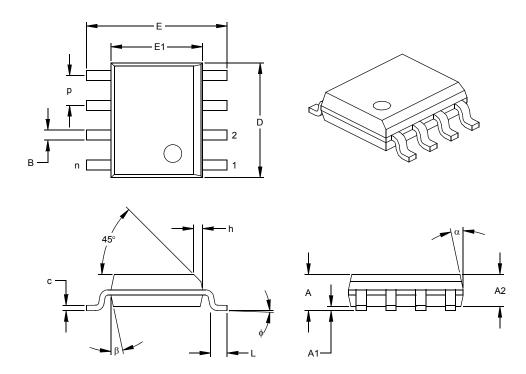
	Units		INCHES*		N	IILLIMETERS	3
Dimension	n Limits	MIN	MOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-001

Drawing No. C04-018

^{*} Controlling Parameter § Significant Characteristic

8-Lead Plastic Small Outline (OA) - Narrow, 150 mil Body (SOIC)



	Units		INCHES*		N	IILLIMETERS	6
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050			1.27	
Overall Height	Α	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	ф	0	4	8	0	4	8
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25
Lead Width	В	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

^{*} Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-012

Drawing No. C04-057

APPENDIX A: REVISION HISTORY

Revision A (June 2006)

• Original Release of this Document.

NOTES:	
--------	--

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. X	xx xxx	Ex	amples:	
Device Temper Rang	•	a)	TC4423AVOA:	3A Dual Inverting MOSFET Driver, 8LD SOIC package.
Device:	TC4423A: 3A Dual MOSFET Driver, Inverting TC4424A: 3A Dual MOSFET Driver, Non-Inverting	b)	TC4423AVPA:	3A Dual Inverting MOSFET Driver, 8LD PDIP package.
Temperature Range:	TC4425A: 3A Dual MOSFET Driver, Complementary V = -40°C to +125°C	c)	TC4423AVMF:	3A Dual Inverting MOSFET Driver, 8LD DFN package.
Package: *	MF = Dual, Flat, No-Lead (6x5 mm Body), 8-lead MF713 = Dual, Flat, No-Lead (6x5 mm Body), 8-lead (Tape and Reel) OA = Plastic SOIC (150 mil Body), 8-Lead	a)	TC4424AVOA713:	3A Dual Non-Inverting, MOSFET Driver, 8LD SOIC package, Tape and Reel.
	OA713 = Plastic SOIC (150 mil Body), 8-Lead (Tape and Reel) PA = Plastic DIP, (300 mil body), 8-lead * All package offerings are Pb Free (Lead Free)	b)	TC4424AVPA:	3A Dual Non-Inverting, MOSFET Driver, 8LD PDIP package.
	p=================================	a)	TC4425AVOA:	3A Dual Complementary, MOSFET Driver, 8LD SOIC package.
		b)	TC4425AVPA:	3A Dual Complementary, MOSFET Driver, 8LD PDIP package.

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- · Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not
 mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, Keeloq, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rfPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, Mindi, MiWi, MPASM, MPLIB, MPLINK, PICkit, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, REAL ICE, rfLAB, rfPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance, UNI/O, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2006, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM

CERTIFIED BY DNV

ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona, Gresham, Oregon and Mountain View, California. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200

Fax: 480-792-7277 Technical Support:

http://support.microchip.com

Web Address: www.microchip.com

Atlanta

Alpharetta, GA Tel: 770-640-0034 Fax: 770-640-0307

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago

Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

San Jose

Mountain View, CA Tel: 650-215-1444 Fax: 650-961-0286

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8676-6200 Fax: 86-28-8676-6599

China - Fuzhou

Tel: 86-591-8750-3506 Fax: 86-591-8750-3521

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Shunde

Tel: 86-757-2839-5507 Fax: 86-757-2839-5571

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7250 Fax: 86-29-8833-7256

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-4182-8400 Fax: 91-80-4182-8422

India - New Delhi

Tel: 91-11-5160-8631 Fax: 91-11-5160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Gumi

Tel: 82-54-473-4301 Fax: 82-54-473-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or

82-2-558-5934

Malaysia - Penang Tel: 60-4-646-8870 Fax: 60-4-646-5086

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870

Fax: 65-6334-8850 **Taiwan - Hsin Chu**

Tel: 886-3-572-9526

Fax: 886-3-572-6459

Taiwan - Kaohsiung Tel: 886-7-536-4818

Fax: 886-7-536-4803

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-399 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham

Tel: 44-118-921-5869 Fax: 44-118-921-5820

02/16/06